

Title (en)

Polishing apparatus and polishing method for silicon wafers

Title (de)

Vorrichtung und Verfahren zum Polieren von Halbleiterscheiben

Title (fr)

Machine et procédé de polissage de plaquettes semi-conductrices

Publication

EP 0798079 B1 20001018 (EN)

Application

EP 97104697 A 19970319

Priority

- JP 6799796 A 19960325
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Abstract (en)

[origin: EP0798079A2] A polishing apparatus and a polishing method of semiconductor wafers are provided, whereby heavy metal contamination of semiconductor wafers can be prevented effectively in a polishing process. A polishing apparatus of semiconductor wafers including a turn table assembly having a rotatably fixed turn table and a polishing slurry tank for storing polishing slurry to be supplied onto the turn table with a polishing slurry supplying member, wherein the polishing slurry supplying member is provided with means for eliminating heavy metal ions from the polishing slurry. <IMAGE>

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